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2019 Hitachi High-Technologies Dry Etch / Plasma Asher

Immediate Availability

Featured Equipment Spotlight
– Issue 01

Overview

Retronix Semiconductor is pleased to present a 2019 Hitachi High-Technologies HS 9050 Dry Etch / Plasma Asher, configured for high-current operation (150A, 3Ø AC 208V).

This 12” multi-chamber platform comprises:

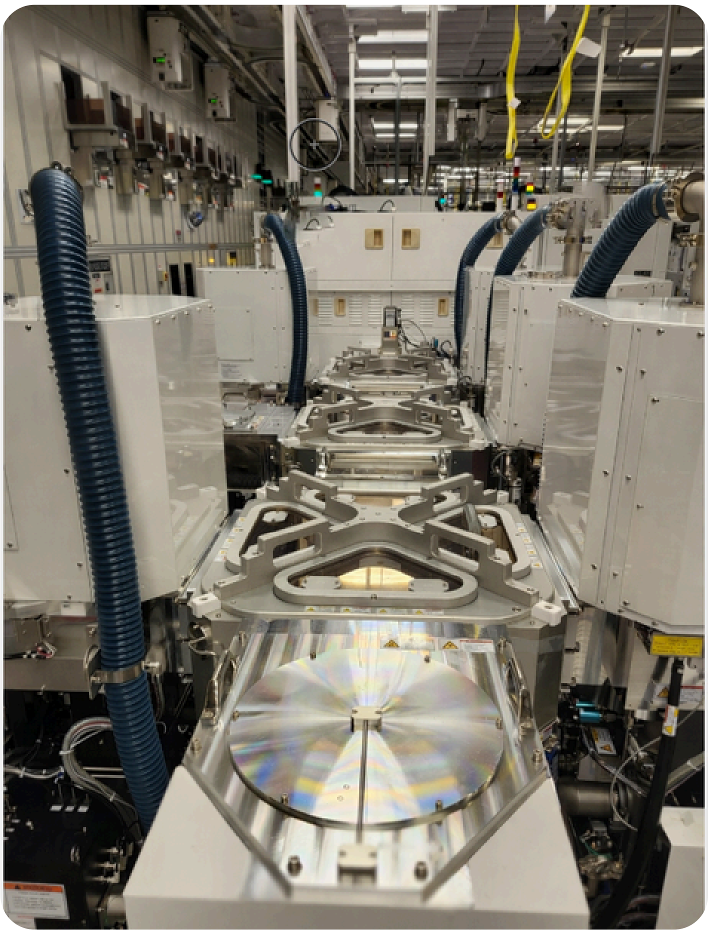
- Five Asher / Etch chambers
- Two Cooling chambers
- Integrated transfer modules
- Mini-Environment Wafer Loading Module (EFEM)

The system is configured for copper processing. HDD has been removed and no software is included.

This is a modern, high-performance platform suited to facilities seeking reliable dry etch capability without extended OEM lead times.

Technical Summary

The 2019 Hitachi High-Technologies Dry Etch / Plasma Asher is engineered for precision processing, optimizing etching and ashing capabilities in semiconductor applications. Its advanced technology ensures uniformity and high throughput, making it ideal for both production and research settings. This equipment is designed to meet stringent industry standards, providing reliability and enhanced performance in the manufacturing process.



The platform highlights of the 2019 Hitachi High-Technologies Dry Etch / Plasma Asher include its state-of-the-art automation features, which streamline the operational workflow. This equipment is compatible with various substrates and materials, enabling flexibility in manufacturing processes. Additionally, its compact design facilitates efficient space utilization in cleanroom environments, ensuring optimal functionality without compromising on quality or performance.

Commercial & Enquiries

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For full technical specifications and commercial discussion, including configuration, pricing, logistics and inspection arrangements, you are invited to contact us directly:
Parts@retronixsemi.com

Single unit availability.
Early discussion is recommended.